

SOT1359-2

HVLGA36, plastic thermal enhanced very thin profile land grid array package; 36 terminals; 5 mm x 5 mm x 0.72 mm body

12 May 2017

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	HVLGA
Package type industry code	HVLGA36
Package style descriptive code	HVLGA (plastic thermal enhanced very thin profile land grid array package)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	28-3-2017
Manufacturer package code	SOT1359

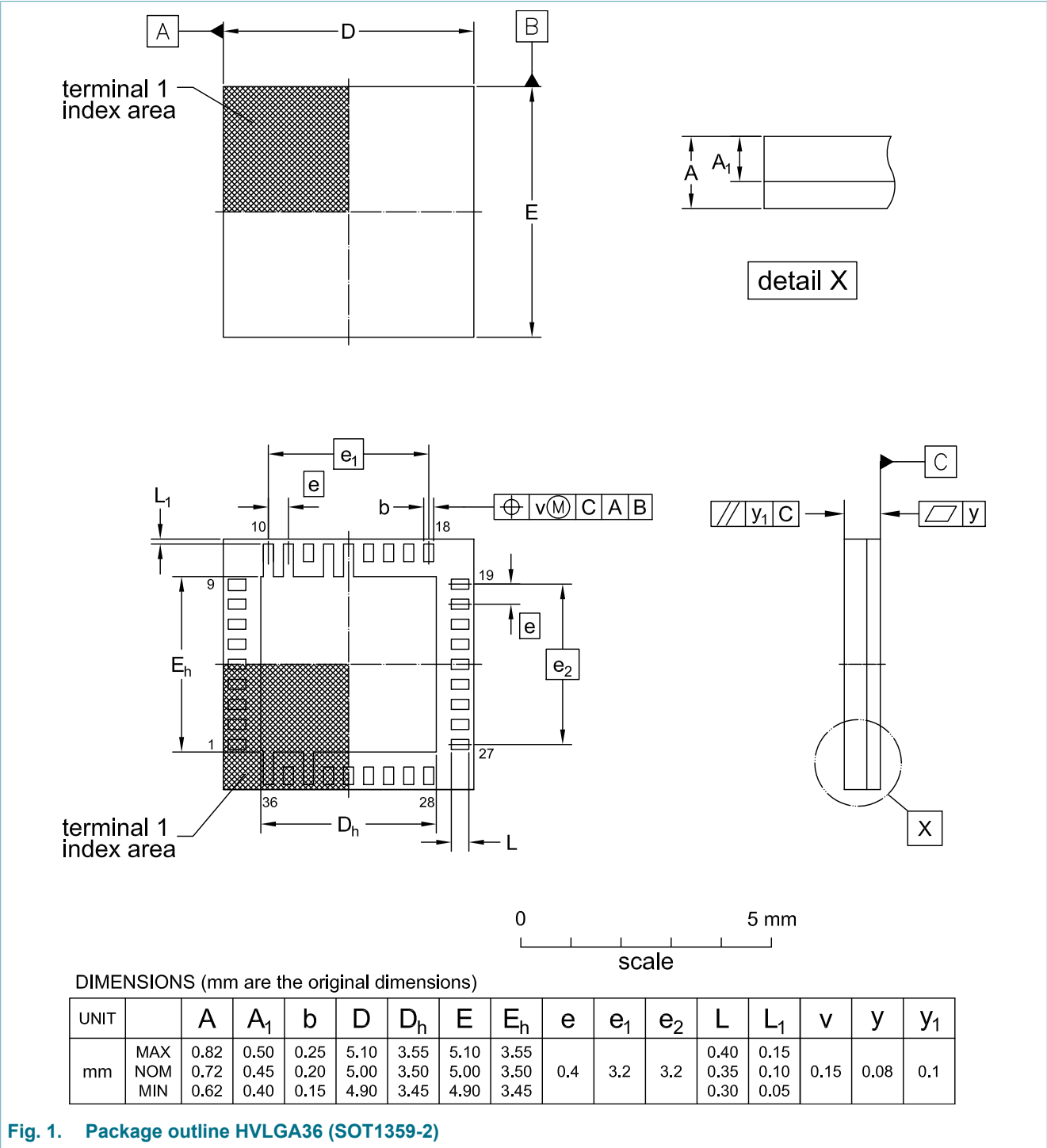
Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		4.9	-	5	5.1	mm
E	package width		4.9	-	5	5.1	mm
A	seated height		0.62	-	0.72	0.82	mm
e	nominal pitch		-	-	0.4	-	mm
n ₂	actual quantity of termination		-	-	36	-	

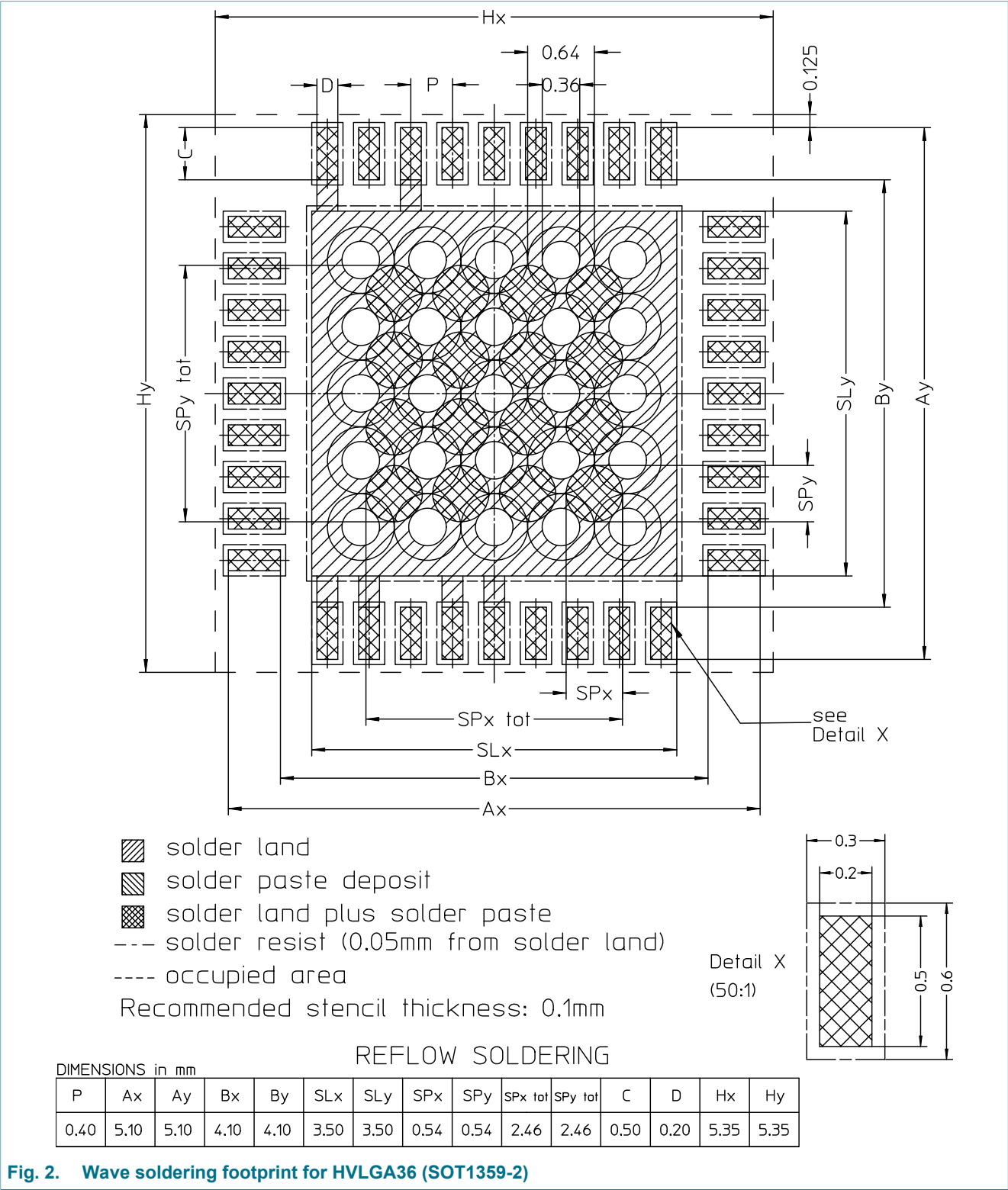


HVLGA36, plastic thermal enhanced very thin profile land grid array package; 36 terminals; 5 mm x 5 mm x 0.72 mm body

2. Package outline



3. Soldering



4. Legal information

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